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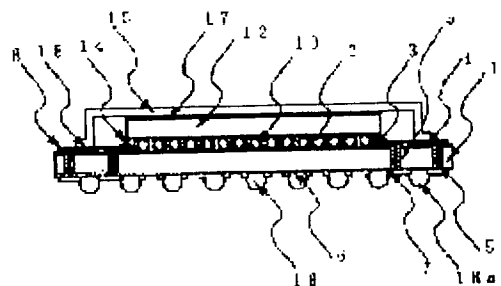
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(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To prevent the radiation of an electromagnetic wave and malfunctions by electromagnetic waves by connecting a metallic cap to a ground of a mother board via the sealing of a substrate 1, a through-hole and outer terminals at the outermost periphery.

SOLUTION: A metallic cap 15 for covering a semiconductor element 12 provided on a substrate 1 is connected to the substrate 1 through a sealing 4 formed on the substrate 1, and a conductive material 16 of solder and anisotropic conductive adhesive. An outer terminals 18 at the outermost periphery, which are connected electrically to the metallic cap 15 is connected to a wiring 7 supplying a ground of a motherboard. Thus, the metallic cap 15 covering the upper faces of the semiconductor element 12 and the substrate 1 becomes ground potential, and a package is electrically shielded from the outside. Since the electromagnetic wave generated when the device operates and an intruded electromagnetic wave are interrupted by the metallic cap 15, the malfunction of a unit due to the discharge/infiltration of the electromagnetic waves can be reduced.



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